

**Sectional Specification: Flex-rigid
multilayer printed boards with through
connections**

EESTI STANDARDI EESSÕNA

NATIONAL FOREWORD

Käesolev Eesti standard EVS-EN 123600:2002 sisaldab Euroopa standardi EN 123600:1996 ingliskeelset teksti. Käesolev dokument on jõustatud 18.12.2002 ja selle kohta on avaldatud teade Eesti standardiorganisatsiooni ametlikus väljaandes. Standard on kättesaadav Eesti standardiorganisatsioonist.	This Estonian standard EVS-EN 123600:2002 consists of the English text of the European standard EN 123600:1996. This document is endorsed on 18.12.2002 with the notification being published in the official publication of the Estonian national standardisation organisation. The standard is available from Estonian standardisation organisation.
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ICS 31.180

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EUROPEAN STANDARD

EN 123600

NORME EUROPÉENNE

EUROPÄISCHE NORM

December 1996

Descriptors: Multilayer printed boards, with through connections, capability test, quality conformance inspection, test patterns

English version

Sectional Specification:
Flex-rigid multilayer printed boards with through connections

Spécification intermédiaire:
Cartes imprimées multicouches
flexorigides avec connexions
transversales

Rahmenspezifikation:
Biegesteife Mehrlagen-Leiterplatten
mit Durchverbindungen

This European Standard was approved on 1992-02-14. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

This European Standard was prepared by CLC/TC CECC/SC 52, Printed boards (former WG 23).

It is based, wherever possible, on the Publications of the International Electrotechnical Commission, and in particular on IEC 326-11, Printed boards, Part 11: Specification for flex-rigid multilayer printed boards with through connections.

The text of the draft based on document CECC(Secretariat)2823 was submitted to the formal vote; together with the voting report, circulated as document CECC(Secretariat)3022, it was approved as EN 123600 on 1992-02-14.

The following dates were fixed:

- latest date by which the EN has to be implemented
at national level by publication of an identical
national standard or by endorsement (dop) 1997-07-01
 - latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) 2003-05-01
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Contents

	Page
1 Introduction.....	4
1.1 Scope and object	4
1.2 Related documents	4
2 General.....	4
3 Test specimen	5
3.1 Capability Approval.....	5
3.2 Quality conformance inspection	5
4 Relevant specification.....	5
5 Characteristics of the printed board.....	6
Table I Basic characteristics.....	6
Table II Additional characteristics.....	16
6 Capability test programme	19
Table III	19
7 Quality conformance inspection	20
Table IV	21
8 Test pattern - Test boards	24
8.1 General.....	24
8.2 Application of test patterns and test boards	24
Table V	25
8.3 Structure of test boards.....	25
8.4 Multiple arrangements of the composite test pattern	25
8.4.1 Examples of multiple arrangements	26
Test board structure, Table VI	27
Figure 3a Layer 1	28
Figure 3b Layer 2	29
Figure 3c Layer 3	30
Figure 3d Layer 4	31
Figure 3e Layer 5	32
Figure 3f Layer 6	33
Figure 3g	34
Figure 3h	35
Figure 4a L specimen (Layer 3, 3a, 3b)	43
Figure 4b L specimen (Layer 4, 4a, 4b)	44
Figure 5 Examples of delamination	45
Figure 6a Methods of reinforcing lands.....	46
Figure 6b Examples relating to access holes.....	47
Figure 7 Examples of soldered holes.....	48

1 Introduction

IEC 326-11 is the IEC Standard for flex-rigid multilayer printed boards with through connections. The following document comprises this IEC Standard and in accordance with the Generic Specification EN 123000, the information additionally necessary for printed boards intended to be handled within the CENELEC system for electronic components of assessed quality.

1.1 Scope and object

This document is a Sectional Specification (SS) relating to flex-rigid multilayer printed boards with through connections irrespective of their method of manufacture, when they are ready for the mounting of the components. It defines the characteristics to be assessed and the test methods to be used for capability approval testing and for quality conformance inspection (lot-by-lot and periodic inspection).

1.2 Related documents

IEC 68	Basic environmental testing procedures
IEC 97	Grid system for printed circuits
IEC 194	Terms and definitions for printed circuits
IEC 249	Metal-clad base materials for printed circuits
IEC 326-1	Printed boards, instructions for the specification writer
IEC 326-2	Test methods for printed boards
IEC 326-3	Recommendations for the design and the use of printed boards
IEC 326-11	Specification for the design and use of flex-rigid multilayer printed boards with through-connections

2 General

This Sectional Specification (SS) applies to flex-rigid printed boards with through-connections and is intended as a basis for the preparation of a

- Capability Detail Specification (CapDS) applying to specific materials e.g. according to IEC 249-2, and to be used for Capability Approval Procedures. It may be necessary to have a CapDS for each type of material. A CapDS may be prepared by an international or national body or by a manufacturer (see also CECC 00 111 / IV).
- Customer Detail Specification (CDS) for the custom built printed boards, according to clause 5 of EN 123000. The CDS will normally be written by the customer and allocated a number within his own system. Further details are also given in EN 123000 and CECC 00 114 / III.

Table I contains the basic characteristics that will normally be important for flex-rigid multilayer printed boards with through-connections and makes reference to the appropriate tests to verify these characteristics.

Table II contains the additional characteristics that may be important for certain flex-rigid multilayer printed boards with through connections and / or certain applications and makes reference to the appropriate tests to verify these characteristics. Where necessary, the relevant specification may quote characteristics and tests from this Table II.

Where additional details for a test have to be specified in the relevant specification, this shall be indicated by "*" in the relevant column. These details shall then be specified in accordance with CECC 00 010 (IEC 326-2).

Table III contains the capability test programme. A specified composite test pattern (CTP) is used as a capability qualifying component.

Table IV contains the information for the quality conformance inspection.

The tables are not intended to prescribe a test sequence. The tests may be carried out in any sequence, unless otherwise specified.